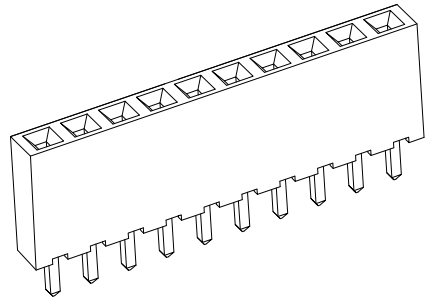
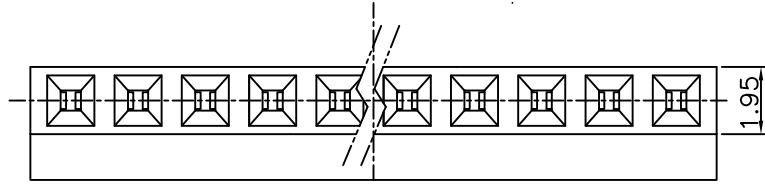


1 2 3 4 5 6 7 8 9

REV.	SPECIFICATION	ECN NO.	APPD.
R4		ECN211031	

A  
B  
C  
D  
E  
F  
G  
H



**Material and Plating:**

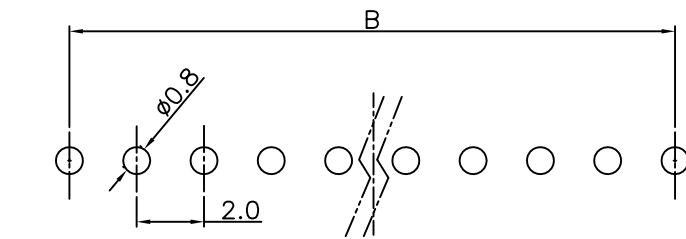
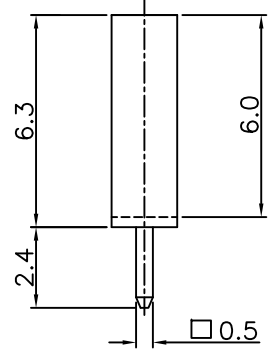
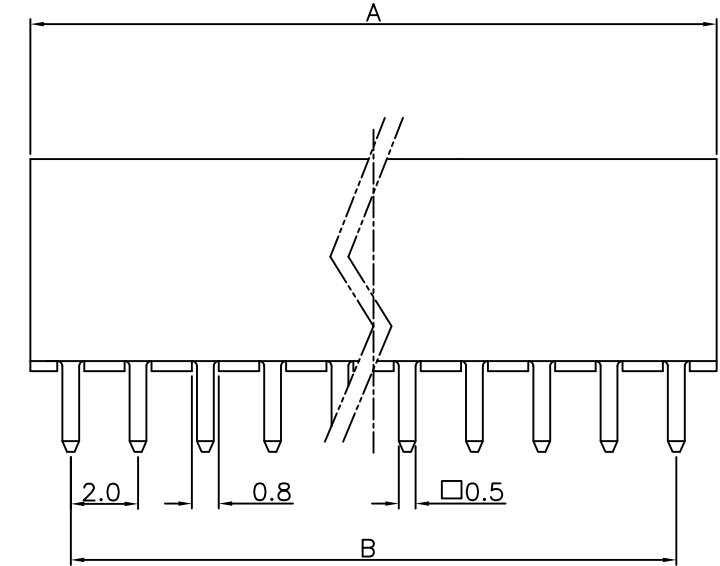
Housing: LCP, UL94V-0, Black.  
 Contacts: Phosphor Bronze.  
 Gold Plated or 80µ" min Tin Plated on Contact Area and 80µ" min Tin or Gold Flash Plated on Solder Tail over Nickel 50µ" Min .

**Electrical Characteristics:**

Current Rating: 1 AMP.  
 Dielectric Withstanding Voltage: AC 500V For 1 Minute  
 Insulator Resistance: 1000MΩ min. at DC 500V.  
 Contact Resistance: 20mΩ max. at DC 10mA.  
 Operating Temperature: -65°C ~+125°C .

**\*RoHS Compliant**

Insertion Depth: 2.30mm to 4.30mm.



P.C. Board Layout  
 (Tolerance: ±0.05)

2145- 1 X xx G xx S A  
 Series  
 Single Row  
 No. of Pin Per Row  
 G: Gold Plated  
 T: Tin Plated  
 C: Selective Gold Plated  
 A: Tray Package  
 S: Straight  
 00: G/F  
 10: 10µ"  
 15: 15µ"  
 30: 30µ"

Position	3 Thru 40
Dimension	
A	2.0 X No. of Position +0.4
B	2.0 X No. of Position -2.0

Tolerances	Dwg. No.	2145D02003	Title:
x = ±0.5	Projection		2145 Series
.x = ±0.25	Unit	mm	P.C.B. Socket 2.0mm(0.079")
.xx = ±0.15	Scale	1:1	
	Drawn By	ZY 10/21'21	

2145 Series  
 P.C.B. Socket 2.0mm(0.079")

**OUPIN**  
**OUPIN ELECTRONIC(KUNSHAN) CO., LTD.**  
 P/N: 2145-1XxxGxxSA  
 SHEET 1/1 Ver. No. R4

1 2 3 4 5 6 7 8 9 10 11 12